Product Information

Lead-free HASL refill alloy FELDER-ISO-Tin® „HAL-Sn100Ni+Refill“

Lead-free refill solder for hot air solder leveling units, RoHS conformity acc. 2011/65/EU
Sn99,9NiGe acc. to Fuji-Pat. No. DE19816671C2, US6179.935, JP3296289

Item-No.: 5512911026

Application

In order to compensate the entry of copper into **“HAL-Sn100Ni+”** in hot air solder levelling units we recommend **“HAL-Sn100Ni+ Refill”**. Hereto a regular control of the solder bath is unavoidable.

Properties

Beside the well-known advantages of Ni-endowed solder our alloy reaches improved wetting qualities and **lowest dross formation** in comparison to all other lead-free solder by the adding of Germanium. For the HAL-application the Ni-endowment was optimized accordingly.
In fact Sn100Ni+ has a lower Cu leaching quote than other lead-free solder, nevertheless a copper level compensation is necessary.

Alloy:	Sn99,9NiGe
Melting point:	232 °C (reduces in the solder bath to 227 ° C!)

Impurities / Tolerances

Sn100Ni+

Element	**Ag**	**Al**	**As**	**Bi**	**Cd**	**Cu**	**Fe**
content (%)	0,003	0,001	0,03	0,06	0,002	< 0,05	0,02

Element	**Ge**	**Ni**	**Pb**	**Sb**	**Sn**	**Zn**
content (%)	0,01 - 0,015	0,12±0,02	0,05	0,1	Rest	0,001

Delivery Forms

400 g - rods, 330 x 20 x 10 mm,

Other alloys are included in our standard delivery program.

Storage

Stored at constant indoor climate durable for an unlimited period!

Status: 03/2018